

# A 60ns 500×12 0.35μm CMOS Low-Power Scanning Read-Out IC for Cryogenic Infra-Red Sensors



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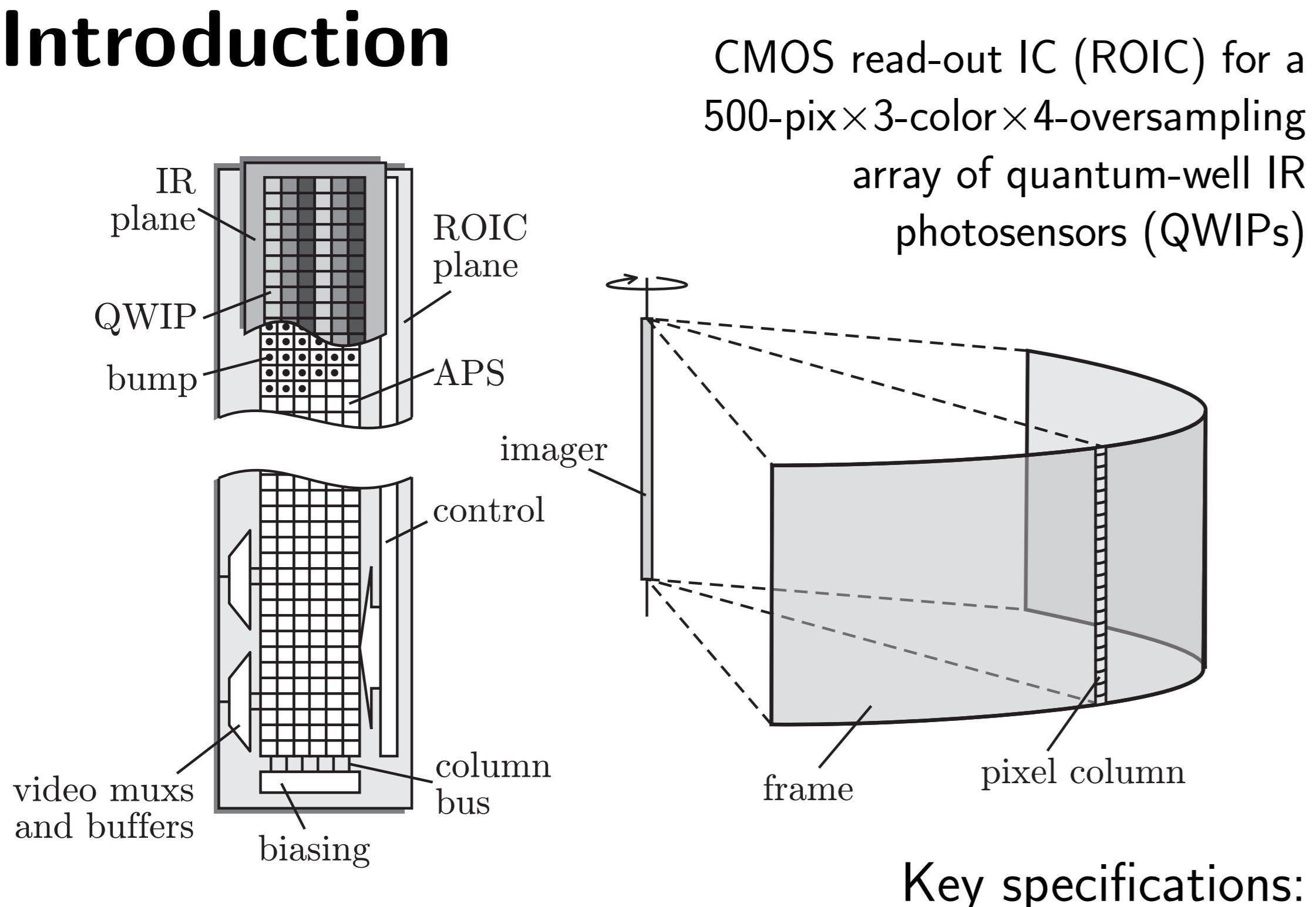
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<http://www.cnm.es/~pserra>



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## 1. Introduction

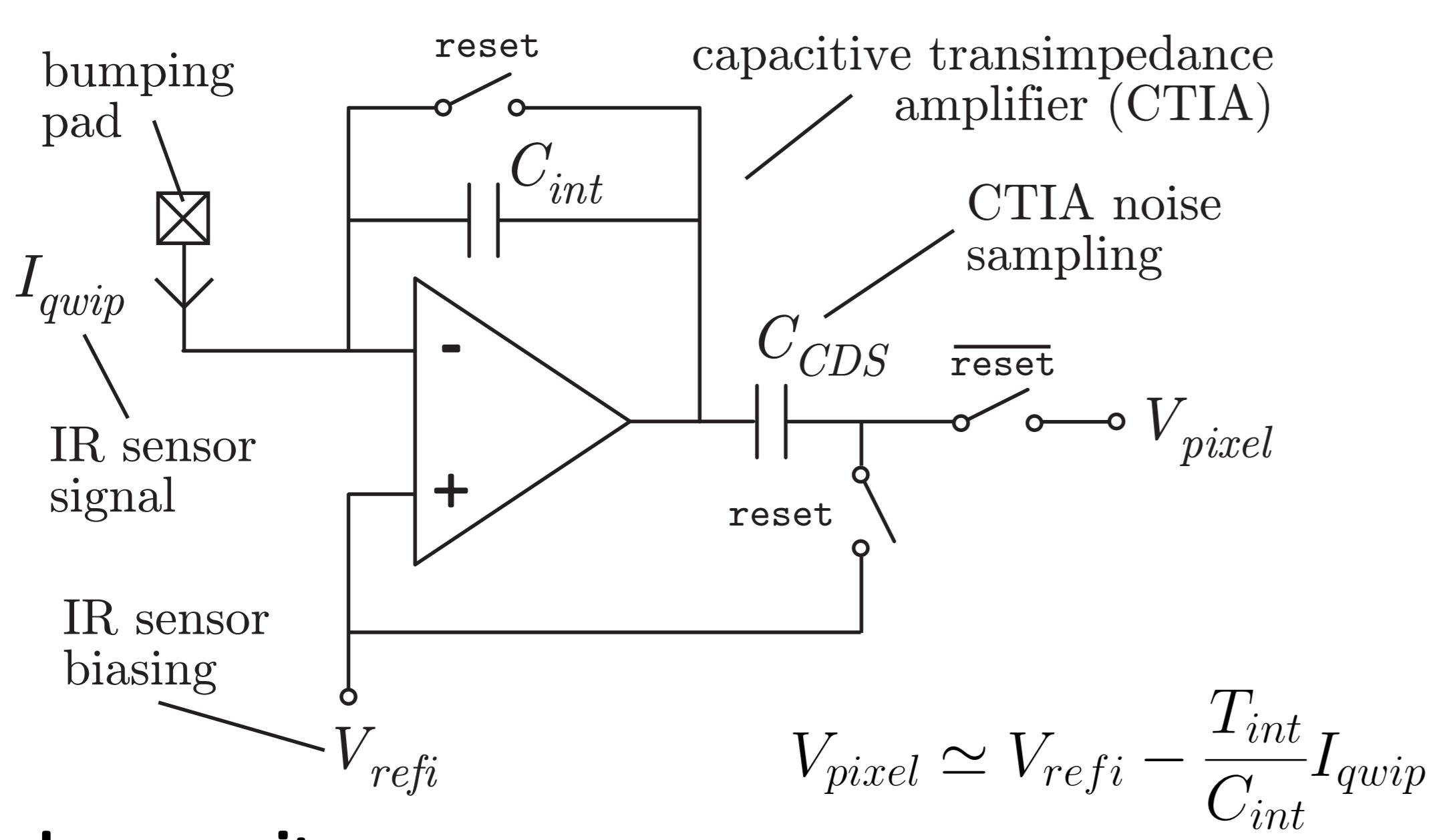


Key specifications:

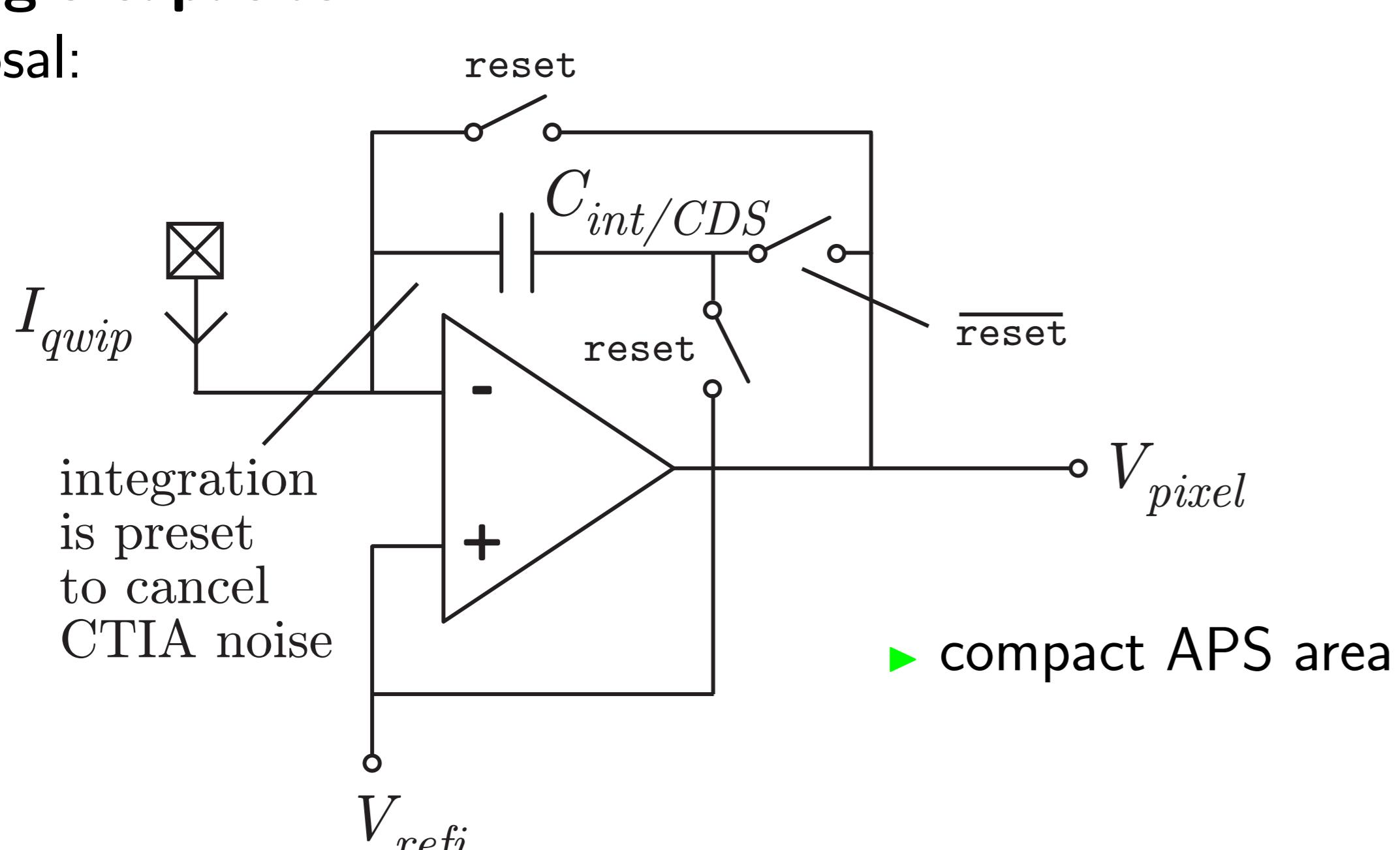
- Cryogenic operation → **low-power** pixel
- Low-cost → **scanning** type and **CMOS** integration
- Real-time video → **high-speed** multiplexing
- High-resolution → **compact** pixel area
- High-sensitivity → correlated double sampling (**CDS**) and time delay integration (**TDI**)

## 2. Active Pixel Sensor (APS)

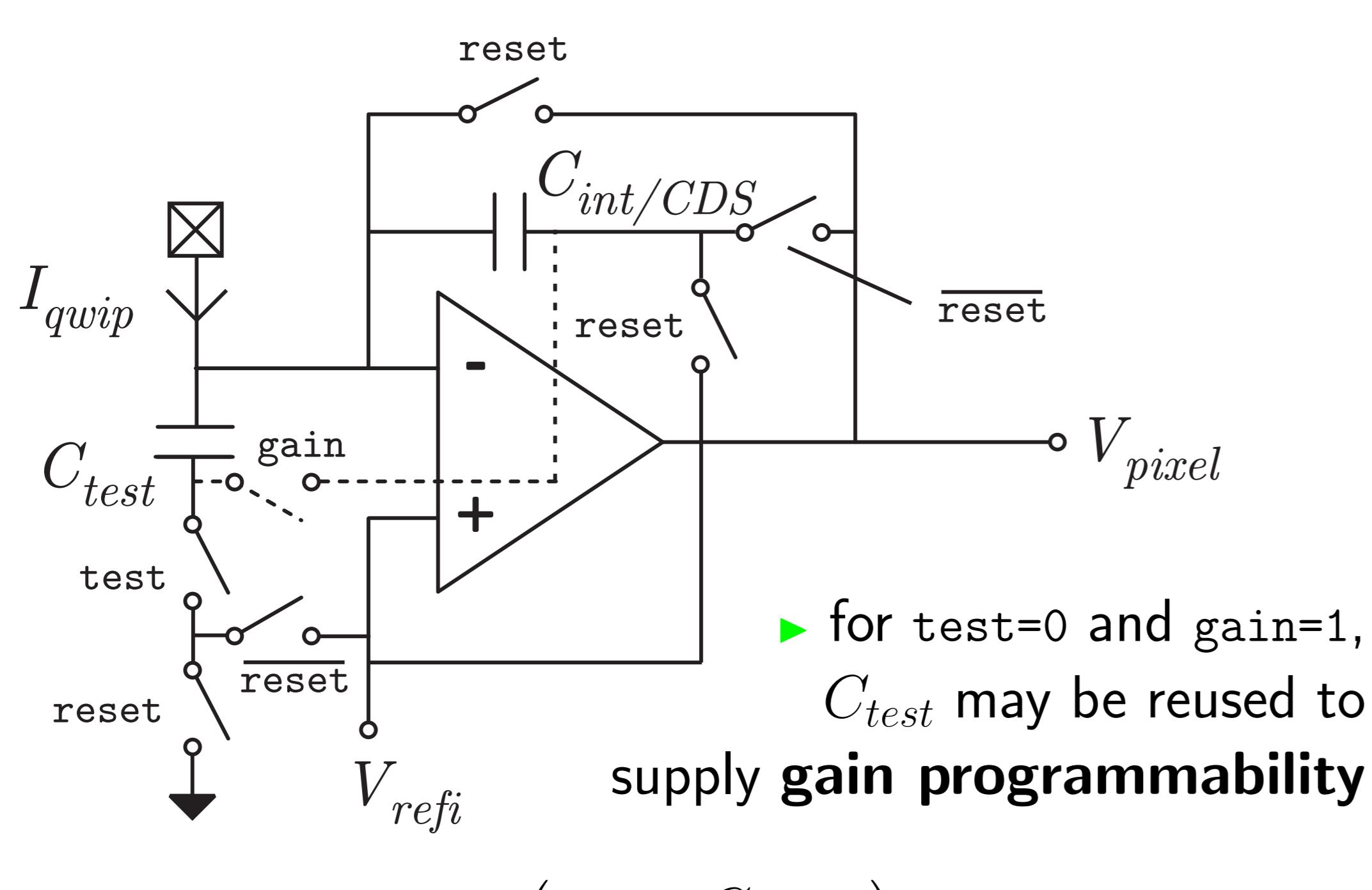
- Classic integrator and CDS cancellation scheme:



- Single-capacitor proposal:



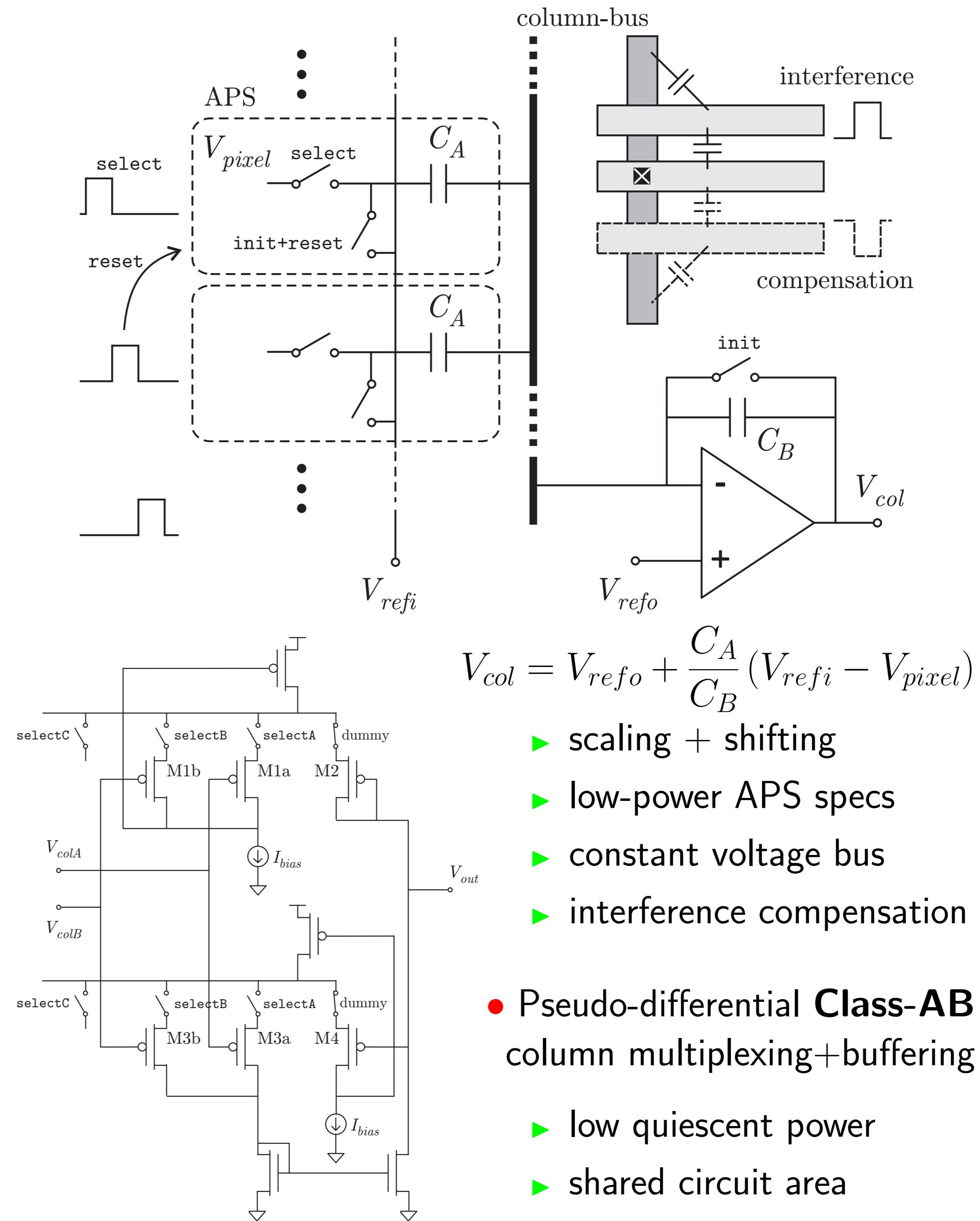
- Proposed embedded pixel-test based on SC:



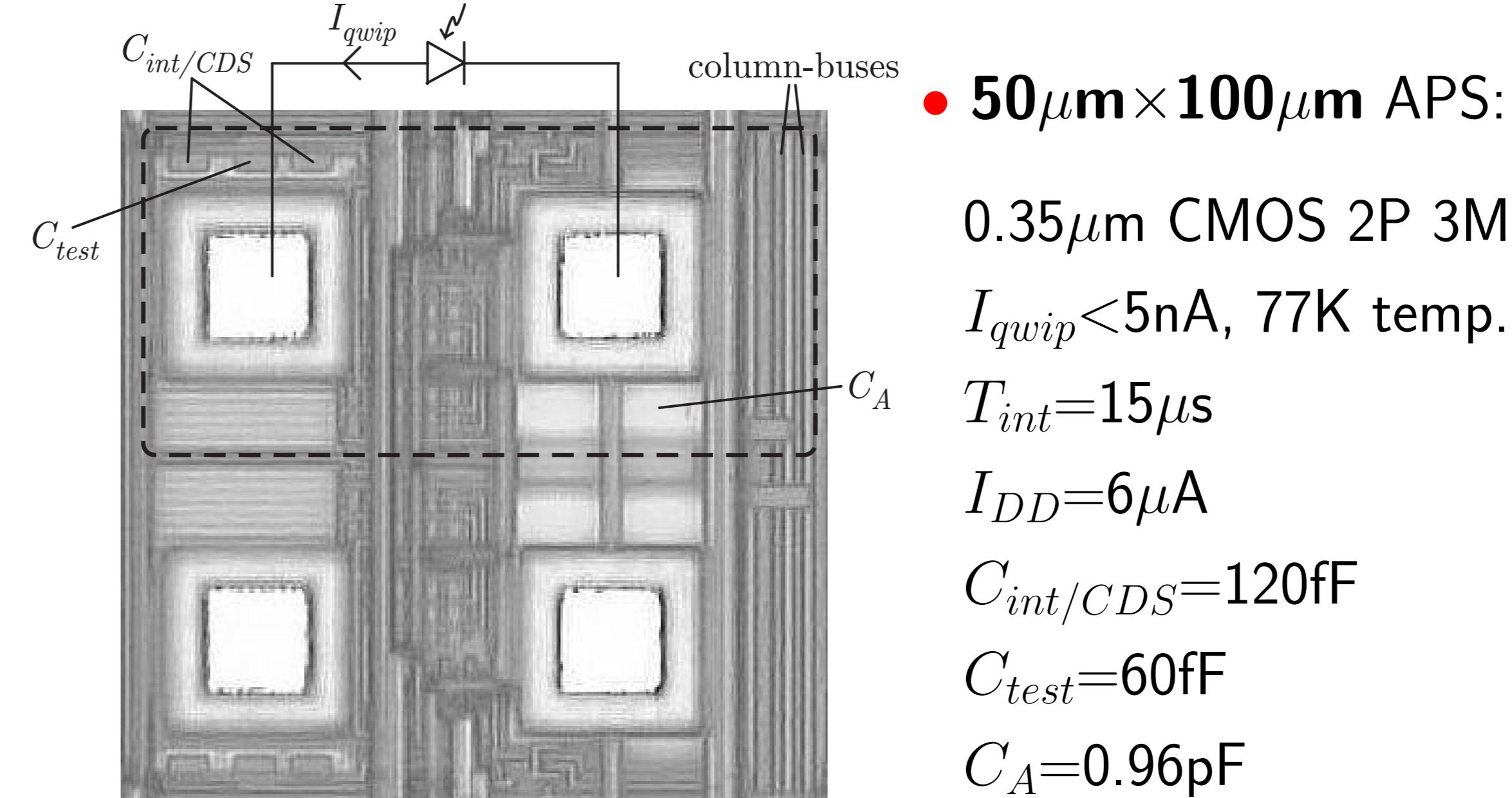
► for test=1,  $V_{pixel} = \left(1 - \frac{C_{test}}{C_{int}/CDS}\right) V_{refi}$

## 3. Video Composition

- Pixel multiplexing in the **charge-domain**:



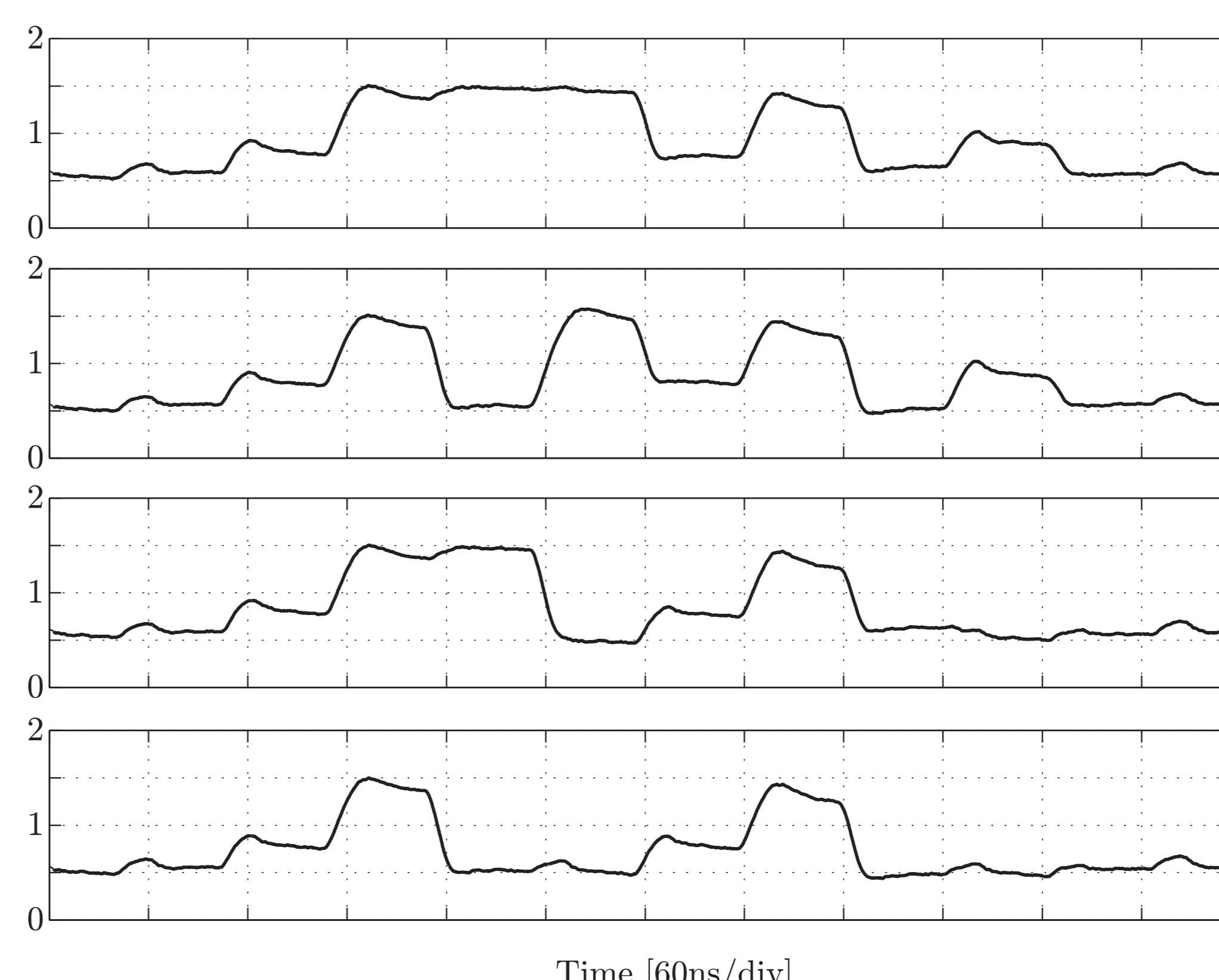
## 4. CMOS Integration



- 50μm×100μm APS:

0.35μm CMOS 2P 3M  
 $I_{qwip} < 5\text{nA}$ , 77K temp.  
 $T_{int}=15\mu\text{s}$   
 $I_{DD}=6\mu\text{A}$   
 $C_{int/CDS}=120\text{fF}$   
 $C_{test}=60\text{fF}$   
 $C_A=0.96\text{pF}$

- Video multiplexing:  $C_B=0.55\text{pF}$ ,  $T_{mux}=60\text{ns}$



## 6. Conclusions

[1] E.Seebacher, "Cryogenic C35 SPICE Models, Private communications from Austria Micro Systems," Sep 2003.

- **Low-power** and **compact** ROIC for **cryogenic** sensors
- Novel built-in **CDS** and **test** per pixel + **charge mux**
- **Adaptable** framing (e.g. 2560×500@25fps)
- Fully integration in **standard CMOS** technology

